

SN54ALS541, SN74ALS540, SN74ALS541 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

SDAS025D – APRIL 1982 – REVISED MARCH 2002

- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- pnp Inputs Reduce dc Loading
- Data Flowthrough Pinout (All Inputs on Opposite Side From Outputs)

description

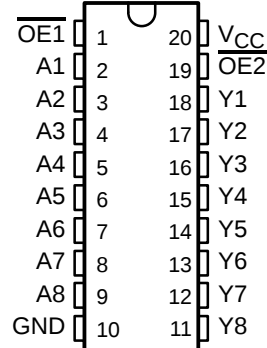
These octal buffers and line drivers are designed to have the performance of the popular SN54ALS240A/SN74ALS240A series and, at the same time, offer a pinout with inputs and outputs on opposite sides of the package. This arrangement greatly facilitates printed circuit board layout.

The 3-state control gate is a 2-input NOR gate such that, if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all eight outputs are in the high-impedance state.

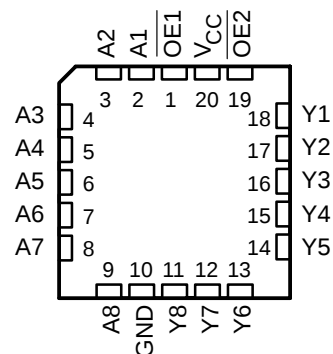
The SN74ALS540 provides inverted data. The 'ALS541 provide true data at the outputs.

The -1 versions of SN74ALS540 and SN74ALS541 are identical to the standard versions, except that the recommended maximum I_{OL} is increased to 48 mA. There is no -1 version of the SN54ALS541.

SN54ALS541 . . . J PACKAGE
SN74ALS540 . . . DW, N, OR NS PACKAGE
SN74ALS541 . . . DB, DW, N, OR NS PACKAGE
(TOP VIEW)



SN54ALS541 . . . FK PACKAGE
(TOP VIEW)



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54ALS541, SN74ALS540, SN74ALS541 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

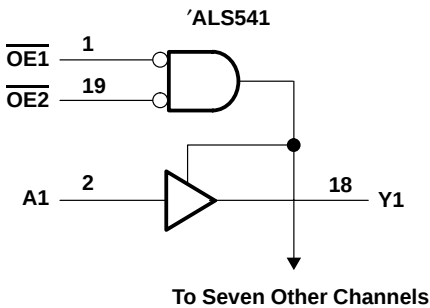
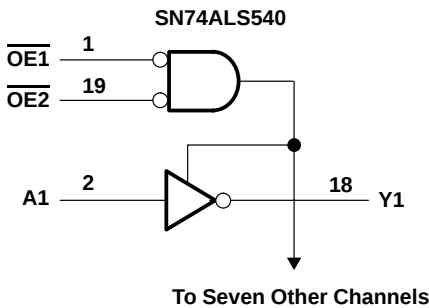
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ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74ALS540N	SN74ALS540N
			SN74ALS540-1N	SN74ALS540-1N
			SN74ALS541N	SN74ALS541N
			SN74ALS541-1N	SN74ALS541-1N
	SOIC – DW	Tube	SN74ALS540DW	ALS540
		Tape and reel	SN74ALS540DWR	
		Tube	SN74ALS540-1DW	ALS540-1
		Tube	SN74ALS541DW	ALS541
		Tape and reel	SN74ALS541DWR	
		Tube	SN74ALS541-1DW	ALS541-1
		Tape and reel	SN74ALS541-1DWR	
	SOP – NS	Tape and reel	SN74ALS540NSR	ALS540
			SN74ALS540-1NSR	ALS540-1
			SN74ALS541NSR	ALS541
			SN74ALS541-1NSR	ALS541-1
	SSOP – DB	Tape and reel	SN74ALS541DBR	G541
			SN74ALS541-1DBR	G541-1
–55°C to 125°C	CDIP – J	Tube	SNJ54ALS541J	SNJ54ALS541J
	LCCC – FK	Tube	SNJ54ALS541FK	SNJ54ALS541FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

logic diagrams (positive logic)



SN54ALS541, SN74ALS540, SN74ALS541 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Package thermal impedance, θ_{JA} (see Note 1): DB package	70°C/W
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		SN54ALS541			SN74ALS540 SN74ALS541			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
I_{OH}	High-level output current			–12			–15	mA
I_{OL}	Low-level output current			12			24	mA
							48 [†]	
T_A	Operating free-air temperature	–55		125	0		70	°C

[†] Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V



SN54ALS541, SN74ALS540, SN74ALS541

OCTAL BUFFERS AND LINE DRIVERS

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ALS541		SN74ALS540 SN74ALS541		UNIT	
				MIN	TYP‡	MAX	MIN		TYP‡
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA		−1.2		−1.2		V	
V _{OH}		V _{CC} = 4.5 V to 5.5 V, I _{OH} = −0.4 mA		V _{CC} − 2		V _{CC} − 2		V	
		V _{CC} = 4.5 V		I _{OH} = −3 mA		2.4 3.2			2.4 3.2
				I _{OH} = −12 mA		2			
				I _{OH} = −15 mA					2
V _{OL}		V _{CC} = 4.5 V		I _{OL} = 12 mA		0.25 0.4		V	
				I _{OL} = 24 mA		0.35 0.5			
				I _{OL} = 48 mA†		0.35 0.5			
I _{OZH}		V _{CC} = 5.5 V, V _O = 2.7 V		20		20		μA	
I _{OZL}		V _{CC} = 5.5 V, V _O = 0.4 V		−20		−20		μA	
I _I		V _{CC} = 5.5 V, V _I = 7 V		0.1		0.1		mA	
I _{IH}		V _{CC} = 5.5 V, V _I = 2.7 V		20		20		μA	
I _{IL}		V _{CC} = 5.5 V, V _I = 0.4 V		−0.2		−0.1		mA	
I _O §		V _{CC} = 5.5 V, V _O = 2.25 V		−20 −112		−30 −112		mA	
I _{CC}	SN74ALS540	V _{CC} = 5.5 V		Outputs high		5 10		mA	
				Outputs low		13 22			
				Outputs disabled		11 19			
	ALS541	V _{CC} = 5.5 V		Outputs high		6 14			
				Outputs low		15 25			
				Outputs disabled		13.5 32			

[†] Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V

[‡] All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

[§] The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, I_{OS} .

switching characteristics (see Figure 1)

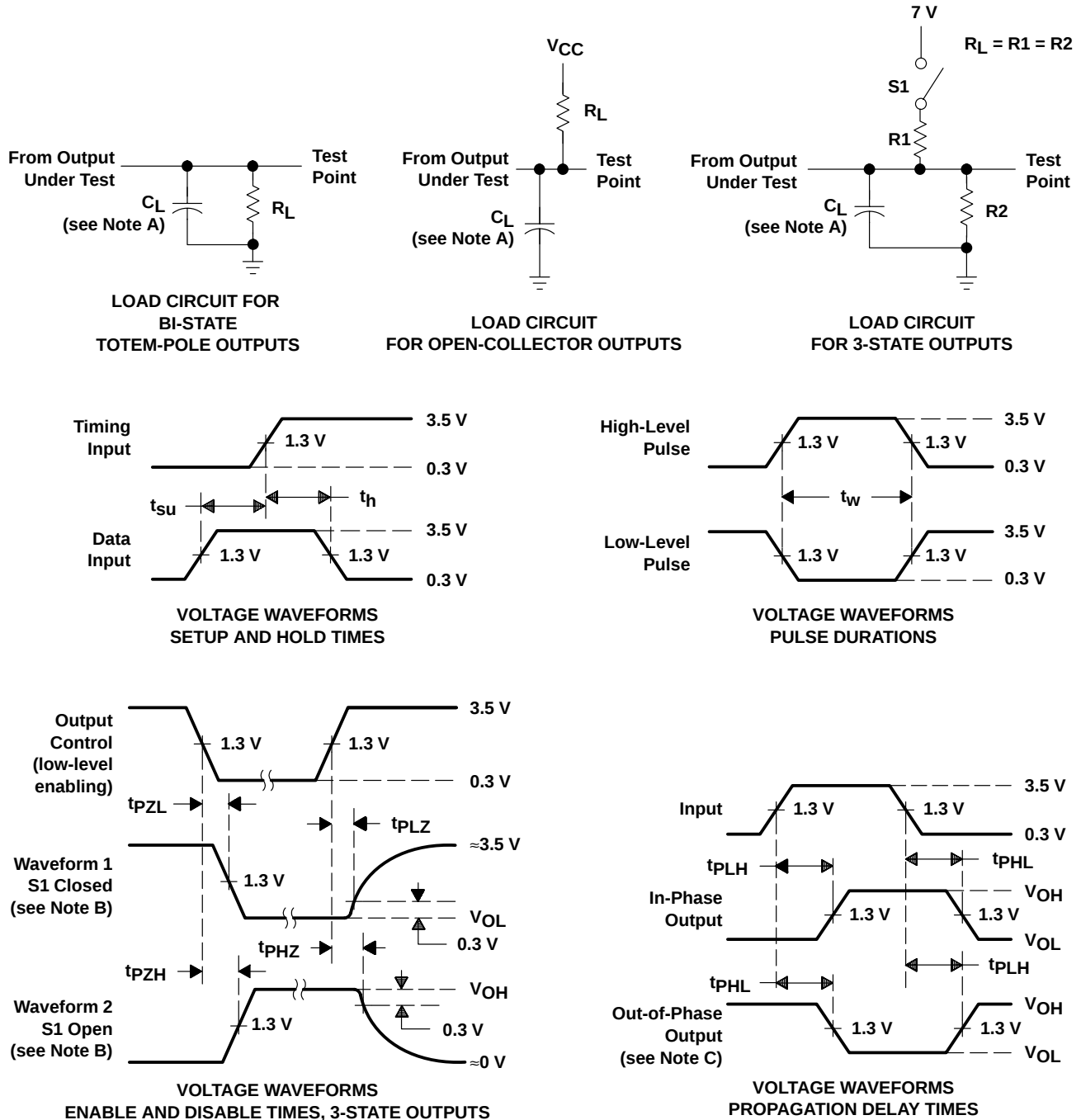
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R ₁ = 500 Ω, R ₂ = 500 Ω, T _A = MIN to MAX††						UNIT
			SN54ALS541		SN74ALS540		SN74ALS541		
			MIN	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	4	17	2	12	4	14	ns
t _{PHL}			2	14	2	9	2	10	
t _{PZH}	$\overline{OE}$	Y	5	18	5	15	5	15	ns
t _{PZL}			8	28	8	20	8	20	
t _{PHZ}	$\overline{OE}$	Y	1	12	1	10	1	10	ns
t _{PLZ}			2	14	2	12	2	12	

^{††} For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

SN54ALS541, SN74ALS540, SN74ALS541 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8960201RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8960201RA SNJ54ALS541J	Samples
5962-8960201SA	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI	-55 to 125		
SN54ALS541J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS541J	Samples
SN74ALS540-1DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS540-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS540-1N	Samples
SN74ALS540-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS540-1	Samples
SN74ALS540DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS540	Samples
SN74ALS540DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS540	Samples
SN74ALS540DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS540	Samples
SN74ALS540DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS540	Samples
SN74ALS540N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS540N	Samples
SN74ALS540N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS540NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS540	Samples
SN74ALS540NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS540	Samples
SN74ALS541-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS541-1	Samples
SN74ALS541-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS541-1N	Samples
SN74ALS541-1NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS541-1N	Samples
SN74ALS541-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS541-1	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS541-1NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS541-1	Samples
SN74ALS541DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G541	Samples
SN74ALS541DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G541	Samples
SN74ALS541DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS541	Samples
SN74ALS541DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS541	Samples
SN74ALS541DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS541	Samples
SN74ALS541N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS541N	Samples
SN74ALS541N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS541NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS541N	Samples
SN74ALS541NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS541	Samples
SN74ALS541NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS541	Samples
SN74ALS541NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS541	Samples
SNJ54ALS541J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8960201RA SNJ54ALS541J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS541, SN74ALS541 :

- Catalog: [SN74ALS541](#)

- Military: [SN54ALS541](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS540-1NSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	4.0	24.0	Q1
SN74ALS540DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS540NSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	4.0	24.0	Q1
SN74ALS541-1NSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	4.0	24.0	Q1
SN74ALS541DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ALS541DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS541NSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	4.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS540-1NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ALS540DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS540NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ALS541-1NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ALS541DBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74ALS541DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS541NSR	SO	NS	20	2000	367.0	367.0	45.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within Mil-Std 1835 GDFP2-F20

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



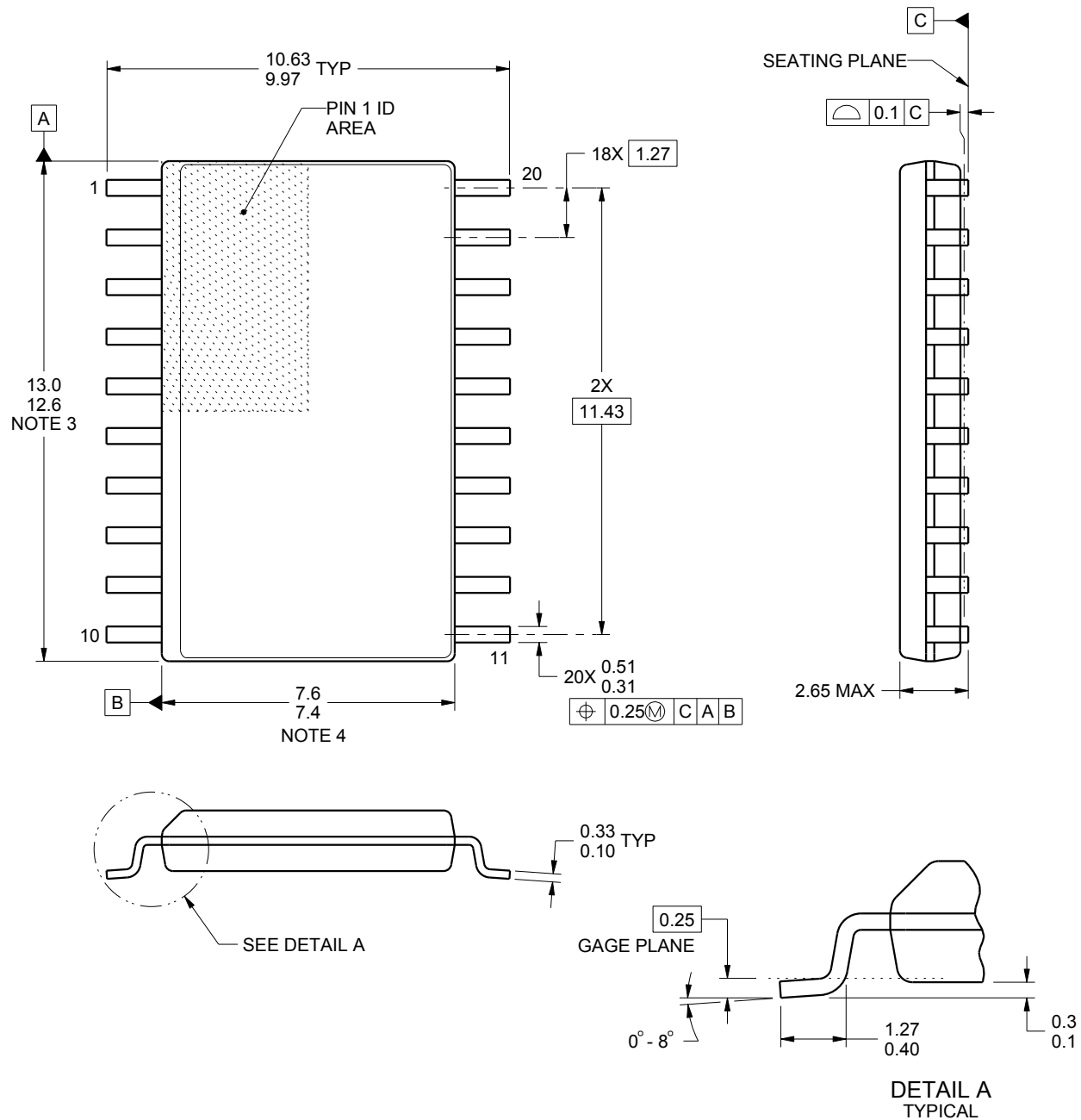
PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



14/18 Pin Only
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.



4220724/A 05/2016

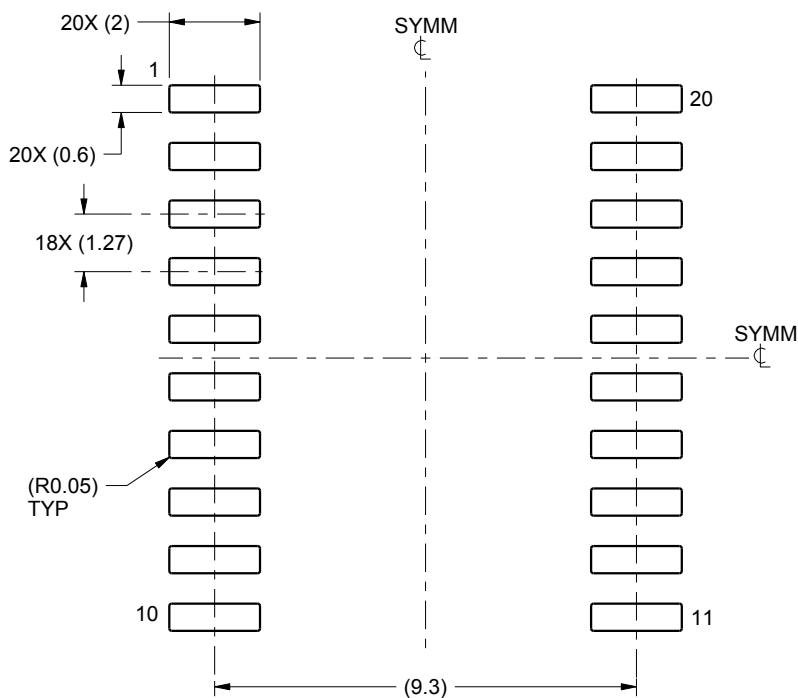
NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

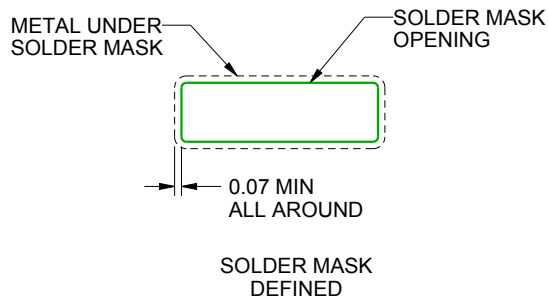
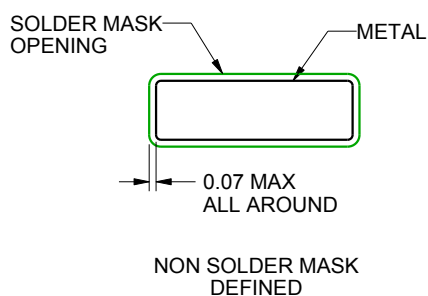
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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